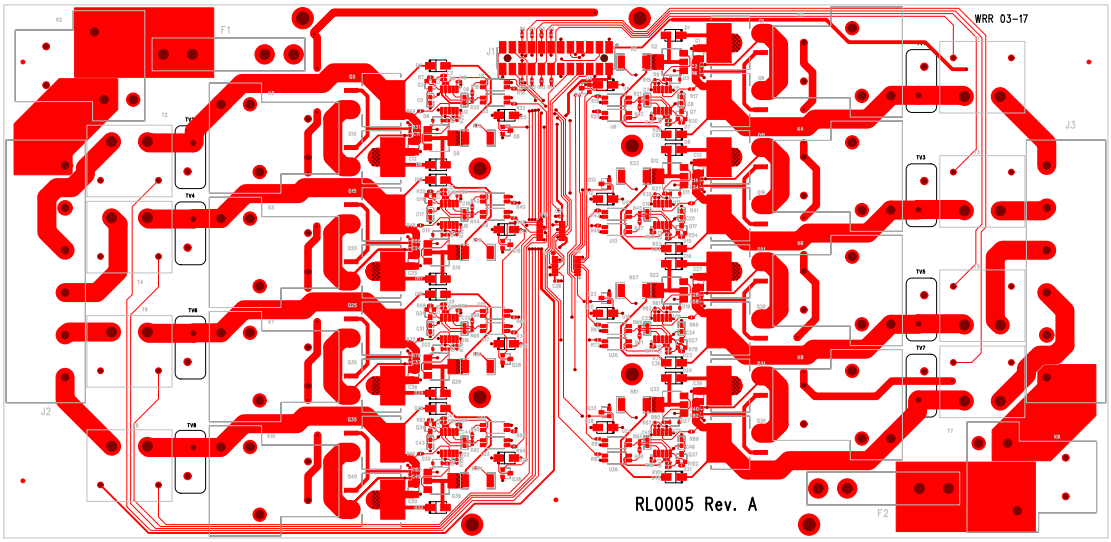


Material Type: 170c FR4
Layer Count: 4
Finished Material Thickness: .062"
Copper Cu Weight: 1/2 plated to 1 oz outer, 1 oz inner
Surface Finish: Immersion Silver
Trace/Space Minimum: .006"
Solder Mask: 2-Sides LPI

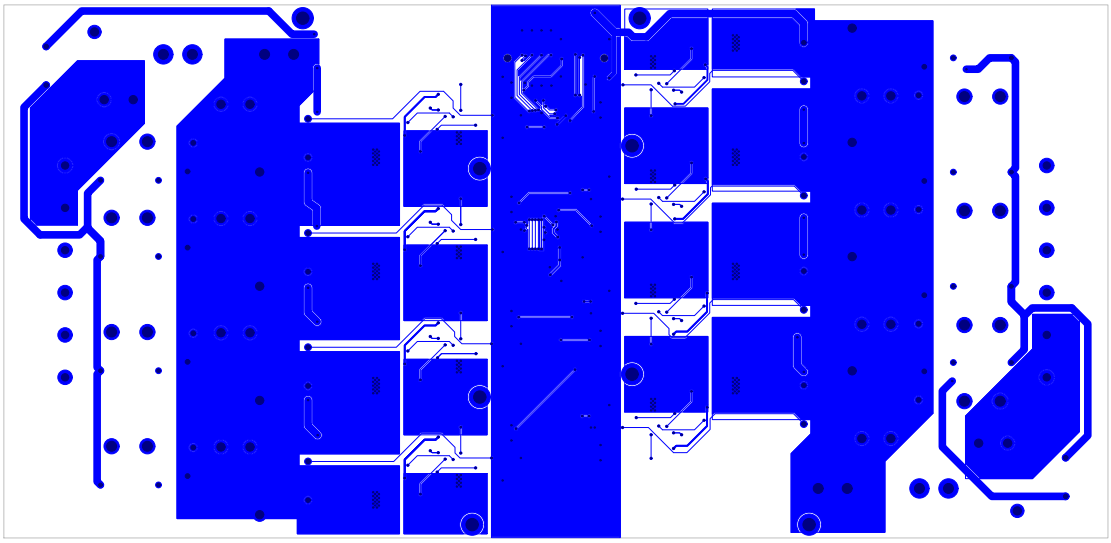
IDColor: White

Fab Specification: IPC-600
Plated Slots: None
Unplated Slots: None
Notches: None
Cutouts: None
Adjust masking undersize as needed for process
Allow clipping in text layer
Board Outline: Dimension lines for reference only
Use Gerber outline
Technical Contact: Ward Ramsdell ward@rds-or.com
Cell - 503-806-2120

LAYER STACKUP - 4 LAYER

SILKSCREEN (TOP SIDE)	White LPI	
SOLDERMASK (TOP SIDE)	Green LPI	
LAYER 1 (TOP)	Plating: Immersion Silver tot. COPPER + plating	
	Adjust as needed	
LAYER 2	1 oz. COPPER	
	Core: Adjust as needed to achieve board thickness	.062" +/- 10%
LAYER 3	1 oz. COPPER	
	Adjust as needed	
LAYER 4 (BOTTOM)	Plating: Immersion Silver tot. COPPER + plating	
SOLDERMASK (BOTTOM SIDE)	Green LPI	
SILKSCREEN (BOTTOM SIDE)		

Ramsdell Design Services, LLC 7755 SW Cirrus Drive Beaverton, OR 97008 (503) 806-2120	LAYER: TOP (1)
	BOARD NAME: Power Distribution Gateway, High Voltage
	BOARD NUMBER: RL0005 REVISION: A
THIS DRAWING CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE USED WITHOUT WRITTEN PERMISSION FROM RAMSDELL DESIGN SERVICES	PROJECT NAME: Revolution Lighting
COMPONENT SIDE VIEW	DESIGNER: W. Ramsdell ENGINEER:



Material Type: 170c FR4
Layer Count: 4
Finished Material Thickness: .062"
Copper Cu Weight: 1/2 plated to 1 oz outer, 1 oz inner
Surface Finish: Immersion Silver
Trace/Space Minimum: .006"
Solder Mask: 2-Sides LPI

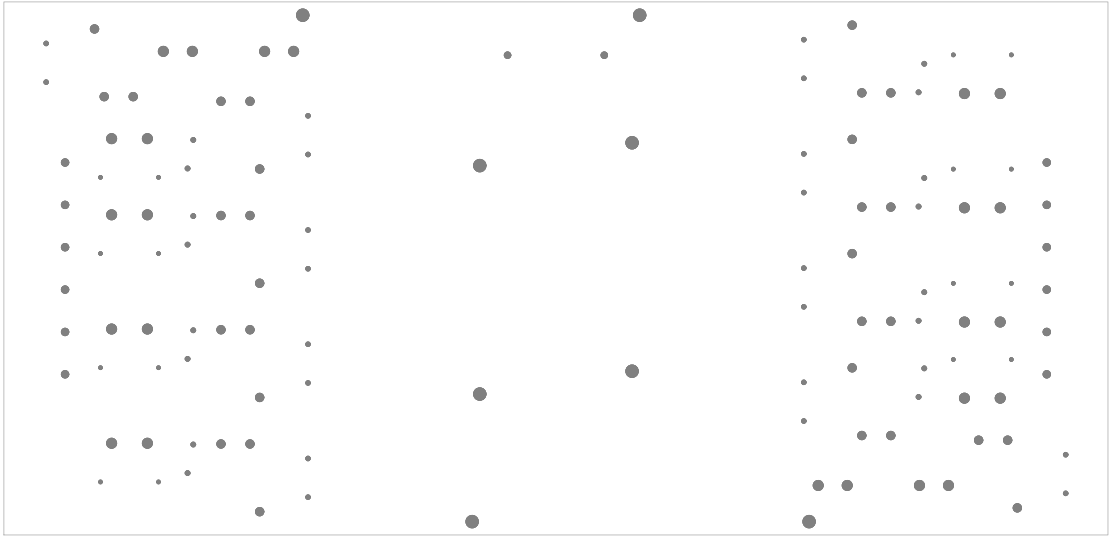
IDColor: White

Fab Specification: IPC-600
Plated Slots: None
Unplated Slots: None
Notches: None
Cutouts: None
Adjust masking undersize as needed for process
Allow clipping in text layer
Board Outline: Dimension lines for reference only
Use Gerber outline
Technical Contact: Ward Ramsdell ward@rds-or.com
Cell - 503-806-2120

LAYER STACKUP - 4 LAYER

SILKSCREEN (TOP SIDE) White LPI
SOLDERMASK (TOP SIDE) Green LPI
LAYER 1 (TOP) Plating: Immersion Silver Inc. COPPER + plating
Adjust as needed
LAYER 2 1 oz. COPPER
Core: Adjust as needed to achieve board thickness
.062" +/- 10%
LAYER 3 1 oz. COPPER
Adjust as needed
LAYER 4 (BOTTOM) Plating: Immersion Silver Inc. COPPER + plating
SOLDERMASK (BOTTOM SIDE) Green LPI
SILKSCREEN (BOTTOM SIDE)

Ramsdell Design Services, LLC 7755 SW Cirrus Drive Beaverton, OR 97008 (503) 806-2120	LAYER: BOTTOM (6)
	BOARD NAME: Power Distribution Gateway, High Voltage
	BOARD NUMBER: RL0005 REVISION: A
THIS DRAWING CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE USED WITHOUT WRITTEN PERMISSION FROM RAMSDELL DESIGN SERVICES	PROJECT NAME: Revolution Lighting
COMPONENT SIDE VIEW	DESIGNER: W. Ramsdell ENGINEER:



Material Type: 170c FR4
Layer Count: 4
Finished Material Thickness: .062"
Copper Cu Weight: 1/2 plated to 1 oz outer, 1 oz inner
Surface Finish: Immersion Silver
Trace/Space Minimum: .006"
Solder Mask: 2-Sides LPI

IDColor: White

Fab Specification: IPC-600
Plated Slots: None
Unplated Slots: None
Notches: None
Cutouts: None
Adjust masking undersize as needed for process
Allow clipping in text layer
Board Outline: Dimension lines for reference only
Use Gerber outline
Technical Contact: Ward Ramsdell ward@rds-or.com
Cell - 503-806-2120

LAYER STACKUP - 4 LAYER

SILKSCREEN (TOP SIDE) White LPI

SOLDERMASK (TOP SIDE) Green LPI

LAYER 1 (TOP) Plating: Immersion Silver tot. COPPER + plating

Adjust as needed

LAYER 2 1 oz. COPPER

Core: Adjust as needed to achieve board thickness

.062"
+/- 10%

LAYER 3 1 oz. COPPER

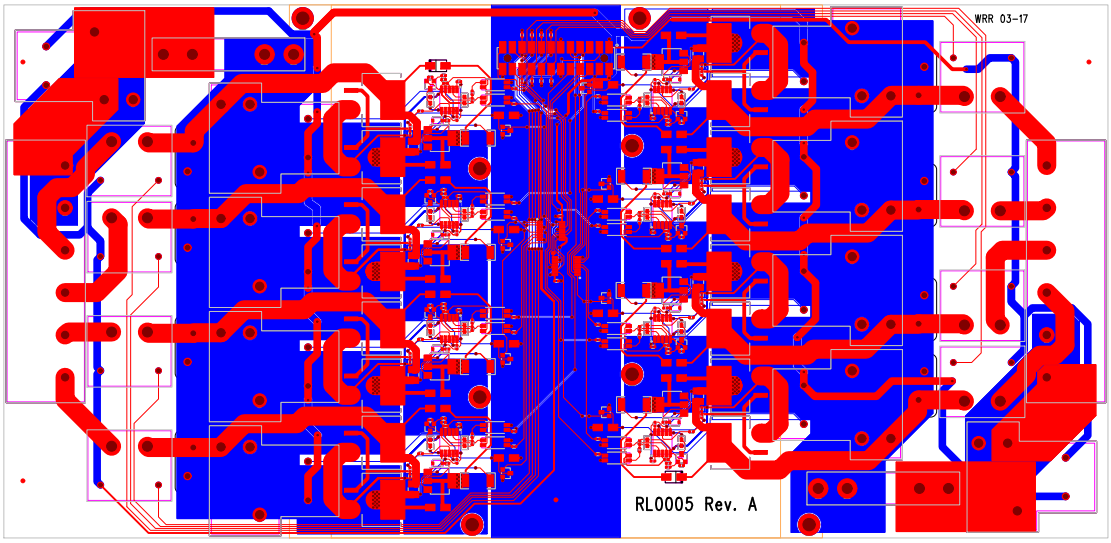
Adjust as needed

LAYER 4 (BOTTOM) Plating: Immersion Silver tot. COPPER + plating

SOLDERMASK (BOTTOM SIDE) Green LPI

SILKSCREEN (BOTTOM SIDE)

Ramsdell Design Services, LLC 7755 SW Cirrus Drive Beaverton, OR 97008 (503) 806-2120	LAYER:
	BOARD NAME: Power Distribution Gateway, High Voltage
	BOARD NUMBER: RL0005 REVISION: A
THIS DRAWING CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE USED WITHOUT WRITTEN PERMISSION FROM RAMSDELL DESIGN SERVICES	PROJECT NAME: Revolution Lighting
COMPONENT SIDE VIEW	DESIGNER: W. Ramsdell ENGINEER:



Material Type: 170c FR4
Layer Count: 4
Finished Material Thickness: .062"
Copper Cu Weight: 1/2 plated to 1 oz outer, 1 oz inner
Surface Finish: Immersion Silver
Trace/Space Minimum: .006"
Solder Mask: 2-Sides LPI

IDColor: White

Fab Specification: IPC-600
Plated Slots: None
Unplated Slots: None
Notches: None
Cutouts: None
Adjust masking undersize as needed for process
Allow clipping in text layer
Board Outline: Dimension lines for reference only
Use Gerber outline
Technical Contact: Ward Ramsdell ward@rds-or.com
Cell - 503-806-2120

LAYER STACKUP - 4 LAYER

SILKSCREEN (TOP SIDE) White LPI

SOLDERMASK (TOP SIDE) Green LPI

LAYER 1 (TOP) Plating: Immersion Silver tot. COPPER + plating

Adjust as needed

LAYER 2 1 oz. COPPER

Core: Adjust as needed to achieve board thickness

.062"
+/- 10%

LAYER 3 1 oz. COPPER

Adjust as needed

LAYER 4 (BOTTOM) Plating: Immersion Silver tot. COPPER + plating

SOLDERMASK (BOTTOM SIDE) Green LPI

SILKSCREEN (BOTTOM SIDE)

Ramsdell Design Services, LLC 7755 SW Cirrus Drive Beaverton, OR 97008 (503) 806-2120	LAYER: BOTTOM (6) SILKSCREEN-BOTTOM
	BOARD NAME: Power Distribution Gateway, High Voltage
	BOARD NUMBER: RL0005 REVISION: A
THIS DRAWING CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE USED WITHOUT WRITTEN PERMISSION FROM RAMSDELL DESIGN SERVICES	PROJECT NAME: Revolution Lighting
COMPONENT SIDE VIEW	DESIGNER: W. Ramsdell ENGINEER:

Q3
Q14
Q24
Q34